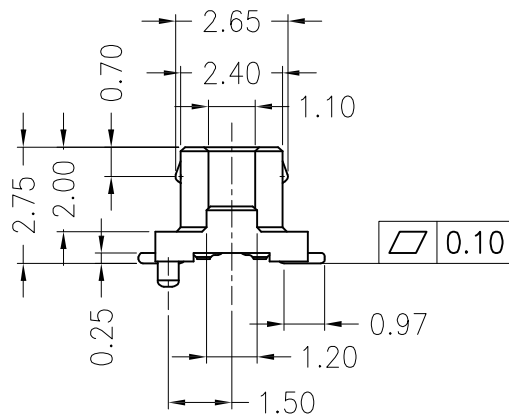
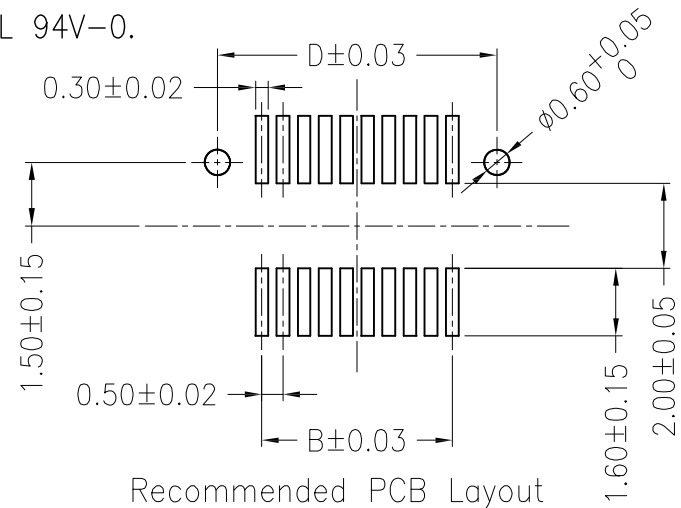


1u" Gold Plating Over all



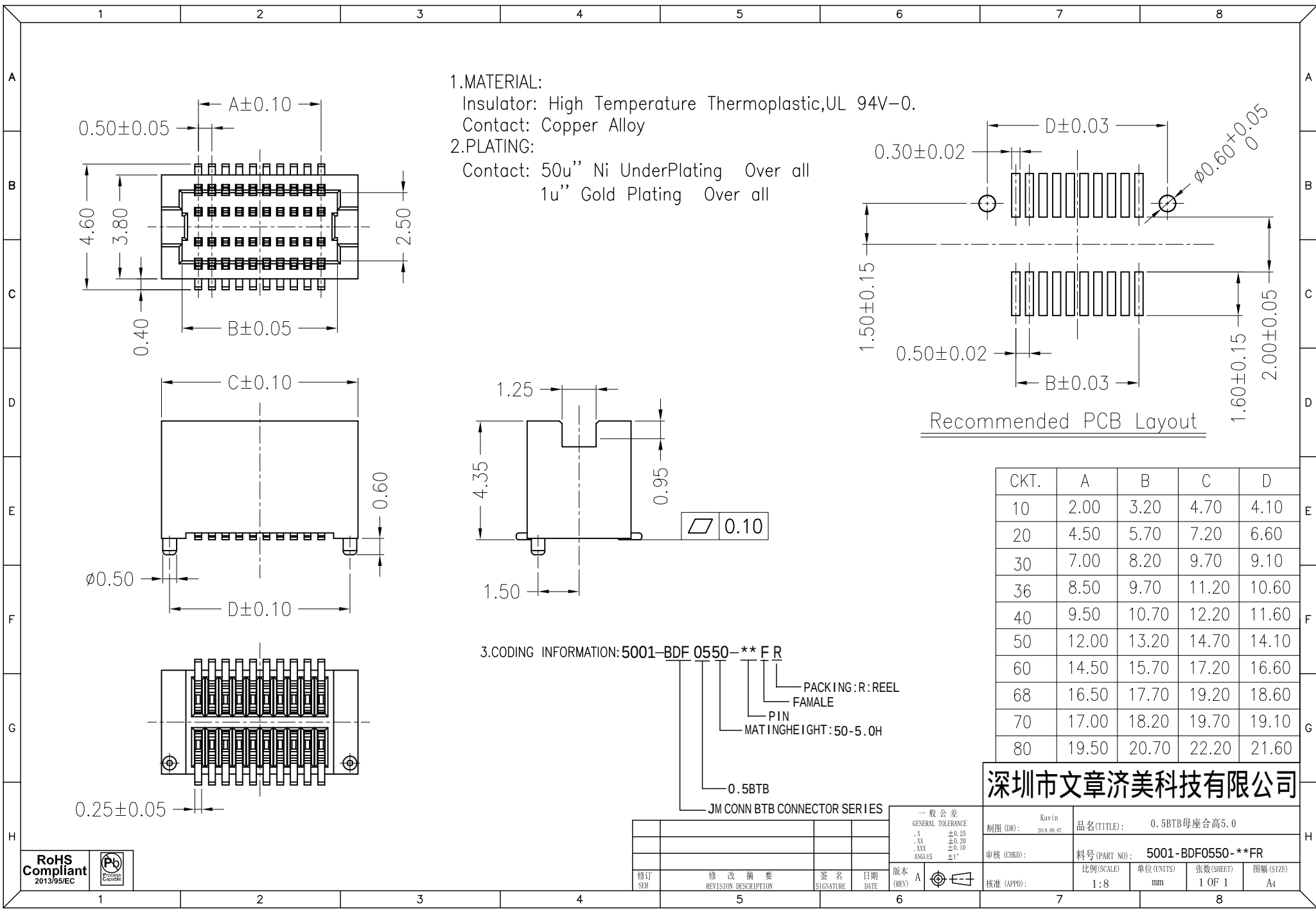
—JM CONN BTB CONNECTOR SERIES



CKT.	A	B	C	D
10	2.00	3.10	4.60	4.10
20	4.50	5.60	7.10	6.60
30	7.00	8.10	9.60	9.10
36	8.50	9.60	11.10	10.60
40	9.50	10.60	12.10	11.60
50	12.00	13.10	14.60	14.10
60	14.50	15.60	17.10	16.60
68	16.50	17.60	19.10	18.60
70	17.00	18.10	19.60	19.10
80	19.50	20.60	22.10	21.60

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				GENERAL TOLERANCE		Kavin		0.5BTB公座高5.0			
				.X ±0.25		制图 (DR):		2018.09.07		品名(TITLE):	
				.XX ±0.20		审核 (CHKD):		料号(PART NO):		5001-BDF0550-**MR	
				.XXX ±0.10							
				ANGLES ±1°							
修订 SER	修 改 摘 要 REVISION DESCRIPTION	签 名 SIGNATURE	日期 DATE	版本 (REV)	A		核准 (APPD):	比例 (SCALE): 1:8	单位 (UNITS): mm	张数 (SHEET): 1 OF 1	图幅 (SIZE): A4



1.MATERIAL:

Insulator: High Temperature Thermoplastic,UL 94V-0.

Contact: Copper Alloy

2.PLATING:

Contact: 50u" Ni UnderPlating Over all

1u" Gold Plating Over all

Recommended PCB Layout

3.CODING INFORMATION:5001-BDF 0550-**-F R

PACKING:R:REEL
FEMALE
PIN
MATING HEIGHT:50-5.0H

0.5BTB
JM CONN BTB CONNECTOR SERIES

CKT.	A	B	C	D
10	2.00	3.20	4.70	4.10
20	4.50	5.70	7.20	6.60
30	7.00	8.20	9.70	9.10
36	8.50	9.70	11.20	10.60
40	9.50	10.70	12.20	11.60
50	12.00	13.20	14.70	14.10
60	14.50	15.70	17.20	16.60
68	16.50	17.70	19.20	18.60
70	17.00	18.20	19.70	19.10
80	19.50	20.70	22.20	21.60

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修订 SER	修改摘要 REVISION DESCRIPTION	签名 SIGNATURE	日期 DATE

一般公差 GENERAL TOLERANCE	版本 (REV)
-X ±0.25	A
-XX ±0.20	
-XXX ±0.10	
ANGLES ±1°	

制图 (DR):	品名(TITLE):
审核 (CHKD):	料号(PART NO):
核准 (APPD):	比例 (SCALE):
	单位 (UNITS):
	张数(SHEET):
	图幅 (SIZE):